



PROCESS CONTROL PLAN

VC 1 DAN VC 2 SMART CARD



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Production Training

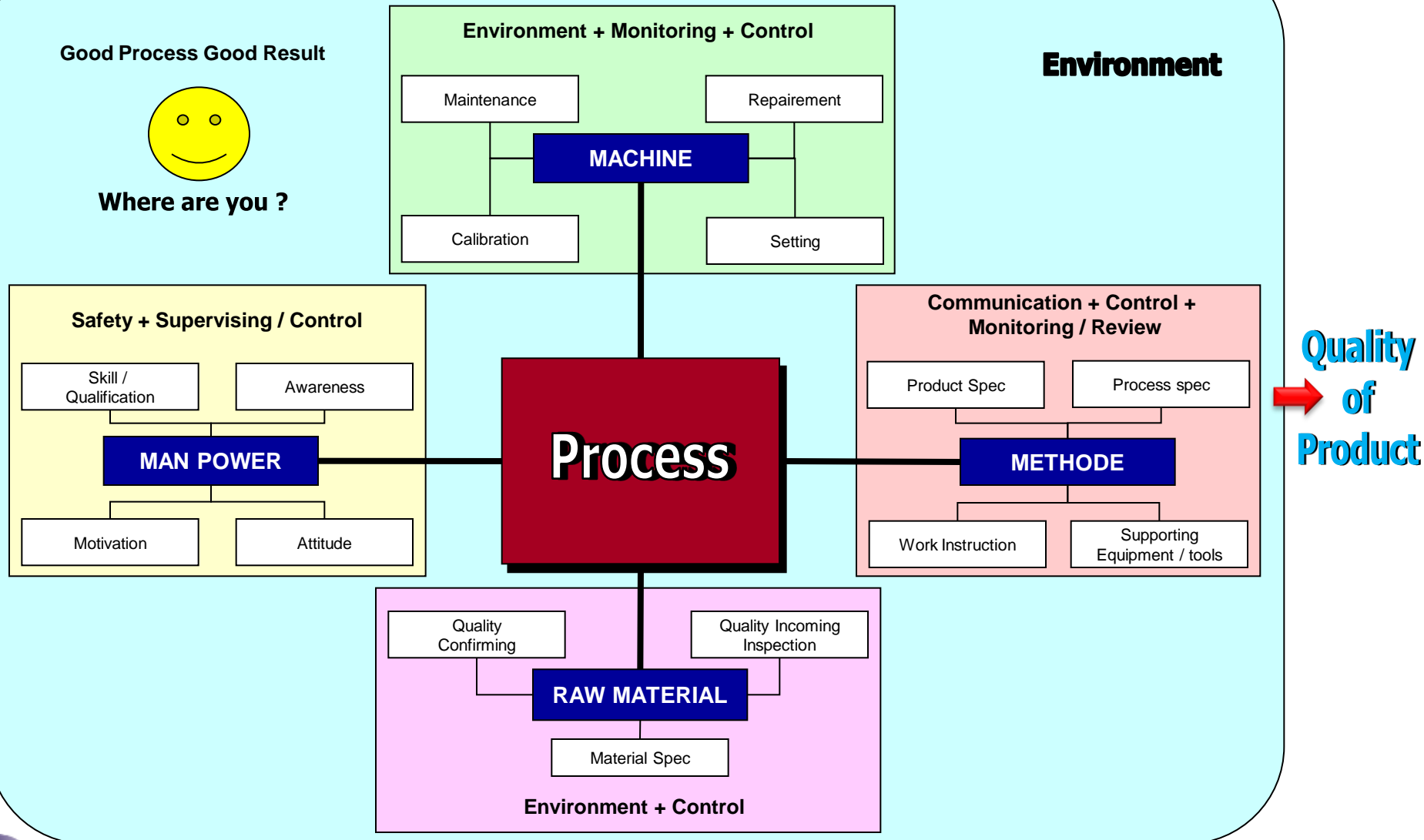
Good Process + Good Attitude → Good Quality + Good Output

Where is your place for contribution to make a Good Quality ??

Good Process Good Result



Where are you ?



PENGERTIAN

- ❑ Proses Control Plan adalah Sistem pengontrolan pada suatu proses yang dilakukan oleh proses Control, Operator dan
- ❑ Leader atau Supervisor.
- ❑ Manufacturing specification adalah Batasan atau spesifikasi suatu produk yang diperbolehkan dari hasil suatu proses.

Proses Condition Table adalah Batasan atau spesifikasi kondisi mesin yang diperbolehkan pada saat proses .

PROCESS CONTROL PLAN

Characteristics			Special Char. Class	Methods				Pic
N0	Product	Process		Product/ Process Specification/Tolerance	Evaluation/ Measurement Technique	Sample		
						Size	Freq	
1		Room Temperature		spec : 23±3°C	Self Temperature	1 point	1x/ day every 9:00 am (+/- 10 min)	PC
2		Humidity		(50 ± 10)% R.H	Hygrometer / Humidity re-corder (A)	1 point	1x/ day every 9:00 am (+/- 10 min)	PC
3		Room Dust Level		≤ 352000 counts	Dust Counter (B)	1 point	1 time/month	PC

PROCESS CONTROL PLAN

Characteristics			Special Char. Class	Methods				Pic
N0	Product	Process		Product/ Process Specification/Tolerance	Evaluation/ Measurement Technique	Sample		
						Size	Freq	
1	Appearance			Refer to Smartcard Reject Criteria for Visual (Doc. No. PO8Hb8-001) Acc =0 Rej = 1	Magnifier (5x) LED Lamp	All units (100%) top and bottom side	Every lot	Operator
2	Lead frame Tape Orientation			Lead Frame Orientation A / B	Magnifier (5x)	All reel	Every lot	Operator

PROCESS CONTROL PLAN

VC 1 & VC 2

1.APPEARANCE CHECK
















Adalah pengecekan semua produk bagian atas dan bawah (100 % check).Dokumen Reject kriteria smartcard Menjadi panduan .

A.Control Plan

Characteristics			Special Char. Class	Methods				Pic
N0	Product	Process		Product/ Process Specification/Tolerance	Evaluation/ Measurement Technique	Sample		
						Size	Freq	
1	Appearance			Refer to Smartcard Reject Criteria for Visual (Doc. No. PO8Hb8-001) Acc =0 Rej = 1	Magnifier (5x) LED Lamp	All units (100%) top and bottom side	Every lot	Operator

B.Reject Kriteria Smartcard



 UTAC-INDONESIA		Title : UID-Smartcard Reject Criteria		Page 7 of 17	
PT. UTAC Manufacturing Service Indonesia		Doc. Number (ID) : PO8Hb8-001			
		Revision No. : 01			
4.2 DIE BOND REJECT CRITERIA					
Reject Name	Description	Defect Picture / Illustration	Good unit Picture	Equipment	JUDGEMENT
Insufficient Blue Tinting	The glue paste that covers the chip back. It can be seen to any blue tinting. Photo edge of chip.			Microscope	Reject if the amount of blue tinting around edge of chip > 80%
Glue Coverage	The glue paste coverage area on the chip. Discoloration or uneven off color.			Microscope	Reject if the coverage of the glue paste is not on the back of the chip < 75%.
Glue Coated	The glue paste that is visible on the chip surface.			Microscope	Reject if the glue paste is visible on the surface of the chip.
Glue Placement	Chip placement position is shifted from the center area of the pad.			Measuring Microscope	Reject if the chip placement position is shifted > 0.1mm in XY direction.
Lifted Die	Chip is not in the bonding process.			Microscope	Reject if any chip is not in the bonding process. Lead frame side.
Chip Bent	Any chip that shows visible bent on the surface.			Microscope	Any defect on chip is not allowed.
Glue Release agent position incorrect	Release agent position should be center on the chip. (Not on the edge).			Microscope	Reject if release agent position is not in the center of the chip.

Sample check :
All unit (100%) Top & Bottom

Frekuensi :
Every Lot

Pic :
operator

PROCESS CONTROL PLAN

VC 1 & VC 2

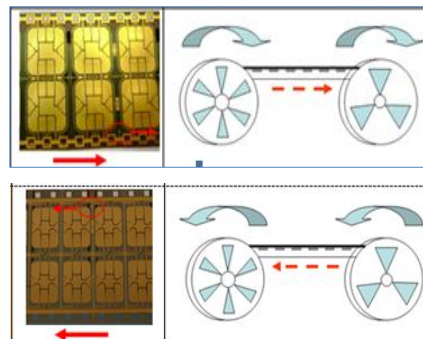
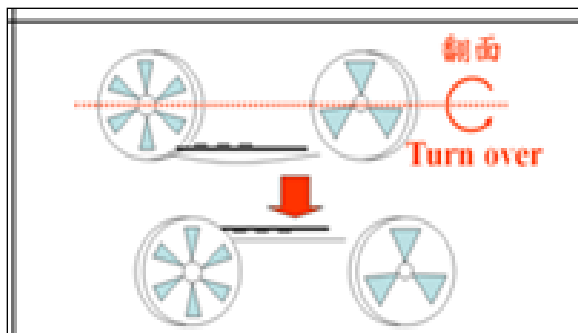
2. LEAD FRAME TAPE ORIENTATION

Adalah pengecekan Orientasi Lead frame saat proses Visual

A. Control Plan

Characteristics			Special Char. Class	Methods				Pic
N0	Product	Process		Product/ Process Specification/Tolerance	Evaluation/ Measurement Technique	Sample		
						Size	Freq	
2	Lead frame Tape Orientation			Lead Frame Orientation A / B	Magnifier (5x)	All reel	Every lot	Operator

B. Orientasi LF



Sample check :
All Reel

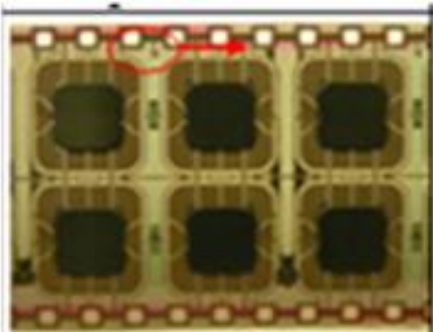
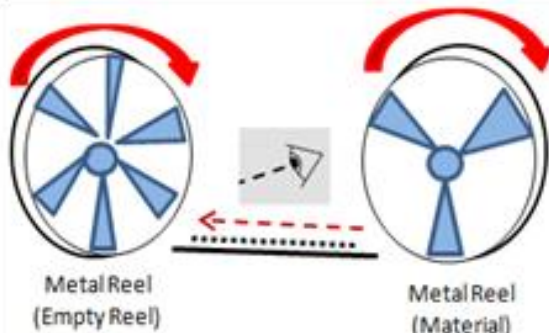
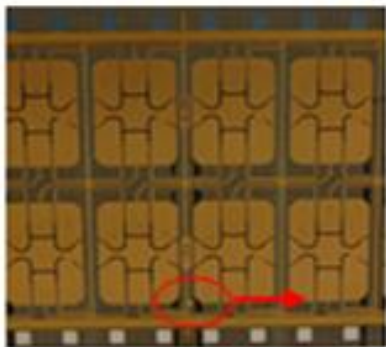
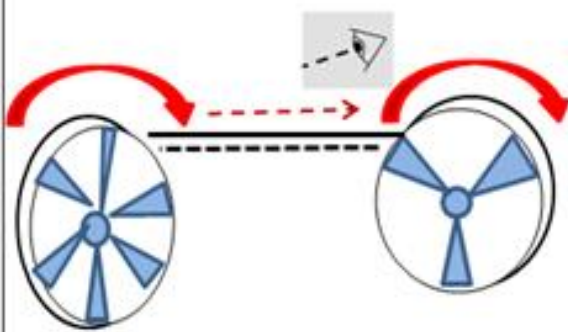
Frekuensi :
Every Lot

Pic :
operator

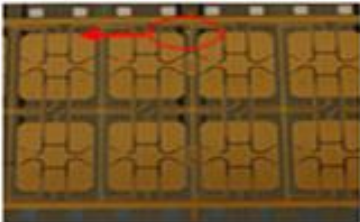
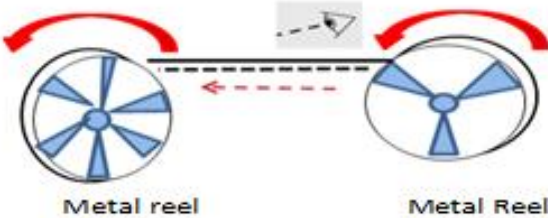
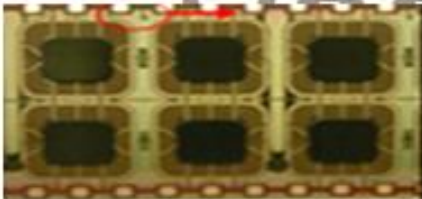
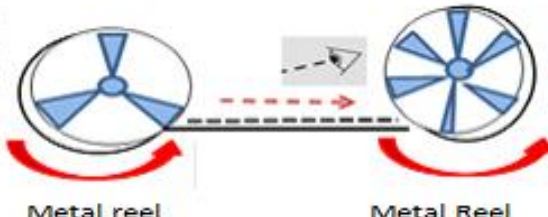

ORIENTASI PRODUK SAAT PROSES

VC 1 & VC 2

INSPECTION DIRECTION VC1

FOR ALL PRODUCT			
Station	Step	Tape Derection	Working Direction
VC 1	Step -1 Check Mold body side		
VC 1	Step -2 Turn Over all reels to check contact side		

INSPECTION DIRECTION VC2

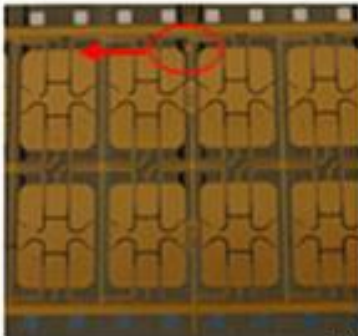
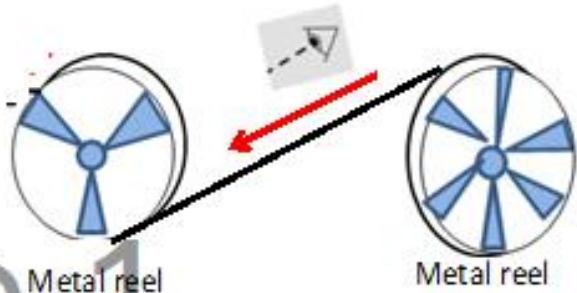
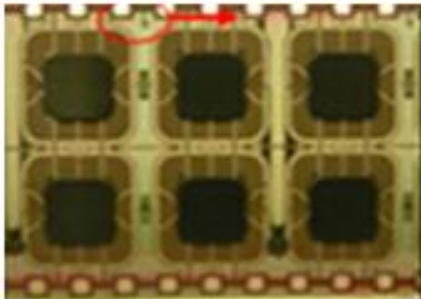
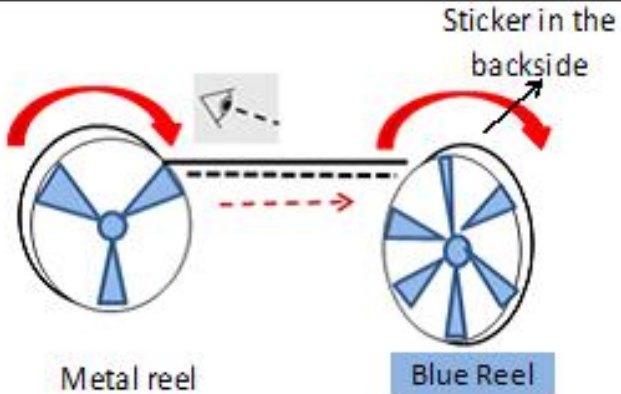
FOR PRODUCT GLOBTOP AND CONTACT 6 - OURANOS			
Station	Step	Tape Orientation	Working Direction
VC 2	Step-1		 <p>Metal reel Metal Reel</p>
	Step-2		 <p>Metal reel Metal Reel</p>
	Step-3	No Inspect, just rotate	 <p>Sticker</p> <p>Blue reel Metal reel</p>

ORIENTASI PRODUK SAAT PROSES

VC 1 & VC 2

INSPECTION DIRECTION VC2

FOR PRODUCT CONTACTLESS & CONTACT 8 – LINXENS

Station	Step	Tape Orientation	Working Direction
VC 2	Step-1		 Metal reel Metal reel
	Step-2		 Metal reel Blue Reel Sticker in the backside